L Number	Hits	Search Text	DB	Time stamp
1	1	5461545.pn. and transparent	USPAT	2002/07/31 14:53
-	1	4300184.pn.	USPAT	2002/02/25 14:26
-	4	chip same (indicia or marking\$) same transparent same cover	USPAT	2002/02/25 14:29
-	39	chip same (indicia or marking\$) same cover	USPAT	2002/02/25 14:35
	62	(semiconductor or chip) same label\$ same cover	USPAT	2002/02/25 14:43
-	0	235/454.pn.	USPAT	2002/02/25 14:43
-	1047	235/454.ccls.	USPAT	2002/02/25 14:43
-	11	235/454.ccls. and (label same cover)	USPAT	2002/02/25 14:48
-	0	235/454.ccls. and (lin.in)	USPAT	2002/02/25 14:48
-	2	235/454.ccls. and (lee.in.)	USPAT	2002/02/25 14:50
-	579	(semiconductor or ic or "integrated circuit" or chip or	USPAT	2002/02/25 15:07
		electronic or device) same (cover or encapsul\$ or coat\$ or		
		layer or packag\$) same transparent same (indicia or label or marking\$)		
_	396	(semiconductor or ic or "integrated circuit" or chip or device)	USPAT	2002/02/25 15:11
	555	same (cover or encapsul\$ or coat\$ or layer or packag\$)	001711	2002/02/20 10:11
		same (indicia or label or mark\$) same identification		
í <u> </u>	144	(semiconductor or ic or "integrated circuit" or chip) same	USPAT	2002/02/25 15:21
	•	(cover or encapsul\$ or coat\$ or layer or packag\$) same	55. / 1	2002/02/20 10.21
		(indicia or label or mark\$) same identification		
	40592	(semiconductor or ic or "integrated circuit" or chip) same	USPAT	2002/02/25 15:22
	10002	(encapsul\$ or packag\$)	00171	2002/02/20 10.22
_	9474	(semiconductor or ic or "integrated circuit" or chip) same	USPAT	2002/02/25 15:41
	5474	(encapsul\$)	OSFAI	2002/02/23 13.41
_	136	(transmissive or transparent) same (marking\$ or indicia)	USPAT	2002/02/25 15:45
-	130	same surface same (chip or ic or circuit)	USFAI	2002/02/23 13.43
_	4	chip same (label or marking or indicia) same (embed\$ or	USPAT	2002/02/25 15:52
-	7	embos\$ or form\$) same surface same cover	USFAI	2002/02/25 15.52
	75	chip same (label or marking or indicia) same (embed\$ or	USPAT	2002/02/25 15:52
-	, 0	embos\$ or imprint\$)	USFAI	2002/02/23 13.32
_	18	chip same (label or marking or indicia) same (embed\$ or	USPAT	2002/02/25 15:55
_	10	embos\$ or imprint\$) same identif\$	USFAI	2002/02/23 13.33
_	11366	(circuit or chip or semiconductor) same (label or marking or	USPAT	2002/02/25 16:00
_	11300	indicia)	USFAI	2002/02/23 10.00
_	1372	((circuit or chip or semiconductor) same (label or marking or	USPAT	2002/02/25 15:59
-	13/2	indicia)) and transparent and cover\$	USPAI	2002/02/25 15.59
	59983		LICOAT	2002/02/25 16:02
-	59965	(circuit or chip or semiconductor) same (label or marking or	USPAT	2002/02/25 16:02
	1050	indicia or code)	LICDAT	2000/00/05 46:06
-	1052	((circuit or chip or semiconductor) same (label or marking or	USPAT	2002/02/25 16:06
		indicia or code)) and transparent and cover\$ and transmi\$		
	207	and mark\$ and identif\$	LICDAT	2002/02/25 40:44
-	227	((circuit or chip or semiconductor) same (label or marking or	USPAT	2002/02/25 16:14
		indicia)) and transparent and cover\$ and transmi\$ and		
	50	mark\$ and identif\$	LICDAT	0000/00/05 40:40
-	59	engrave\$ same surface same indicia and (chip or circuit or	USPAT	2002/02/25 16:19
	2000	semiconductor)	LICCAT	0000/00/05 40 00
-	3008	(engrave\$ or form\$ or emboss) and (markings or indicia or	USPAT	2002/02/25 16:22
	400	code\$) same surface same (chip or circuit or semiconductor)		0000/00/05 40 51
-	422	(engrave\$ or form\$ or emboss) and (markings or indicia or	USPAT	2002/02/25 16:24
		code\$) same surface same (chip or circuit or semiconductor)		
		and 235/\$.ccls.	110015	0000/00/07 10 17
•	47	(engrave\$ or form\$ or emboss\$) and (marking\$ or indicia or	USPAT	2002/02/25 16:48
		code\$) same surface same (chip or circuit or semiconductor)		
		and 235/454.ccls.	l	
-	456	(engrave\$ or form\$ or emboss\$ or etch\$) and (marking\$ or	USPAT	2002/02/25 16:52
		indicia or code\$) same surface same (chip or circuit or		
		semiconductor) same identif\$		
-	23	(engrave\$ or form\$ or emboss\$ or etch\$) and (marking\$ or	USPAT	2002/02/25 17:02
		indicia or code\$) same surface same (chip or circuit or		
		semiconductor) same identif\$ and (transparent same cover)		

	47	(engrave\$ or form\$ or emboss\$ or etch\$ or record) and	USPAT	2002/02/25 17:34
-	4/		USPAI	2002/02/25 17:34
		(marking\$ or indicia or code\$ or data or information) same		
		surface same (chip or circuit or semiconductor) same		
		identif\$ and (transparent same cover)		
-	426	(engrave\$ or form\$ or emboss\$ or etch\$ or record) and	USPAT	2002/02/25 17:43
		(marking\$ or indicia or code\$ or data or information) same		
		surface same (chip or circuit or semiconductor) same		
		identif\$ and cover		
_	65	(engrave\$ or form\$ or emboss\$ or etch\$ or record) and	USPAT	2002/02/25 17:47
		(marking\$ or indicia or code\$ or data or information) same		
		surface same (chip or circuit or semiconductor) same		
		identif\$ same cover		
	347		LICDAT	2002/02/26 00:22
-		color same (barcode or "bar code") same identif\$	USPAT	2002/02/26 09:32
-	48	color\$ adj3 (barcode or "bar code") same identif\$	USPAT	2002/02/26 09:35
-	5	(color and (barcode or "bar code")).ti.	USPAT	2002/02/26 09:36
-	23	(color and (code or tag)).ti.	USPAT	2002/02/26 09:38
_	1246	"bar code" same color	USPAT	2002/02/26 09:38
_	332	"bar code" same color and 235/\$.ccls.	USPAT	2002/02/26 09:41
_	15	(("bar code" or tag or label) and color).ti.	USPAT	2002/02/26 09:47
	23	"colored barcode" or "colored bar code"	USPAT	2002/02/26 10:44
=				
-	4	"microlabel" same color\$	USPAT	2002/02/26 10:52
-	1	5346738.pn. and bar	USPAT	2002/02/26 11:23
-	5039	(cover same transparent) and (code or label or tag or indicia)	USPAT	2002/02/26 11:23
-	1901	(transparent adj3 cover) and (code or label or tag or indicia)	USPAT	2002/02/26 11:26
_	525	(transparent adj3 cover) same ("bar code" or tag or indicia or	USPAT	2002/02/26 11:32
		label)	33,7,1	
	13		LICDAT	2002/02/26 44:26
-		(transparent adj3 cover) same ("bar code") and chip	USPAT	2002/02/26 11:36
-	27	("transparent cover") same ("bar code")	USPAT	2002/02/26 11:39
-	81	cover same ("bar code") same protect\$	USPAT	2002/02/26 11:39
-	26	cover same ("bar code") same protect\$ same (clear or	USPAT	2002/02/26 11:46
		transparent)		
_	44	cover same ("bar code" or indicia) same protect\$ same	USPAT	2002/02/26 11:58
		(semiconductor or circuit or chip)	00.7.	2002/02/20 11:00
	4.4		LIODAT	0000/00/00 44.50
-	44	cover same protect\$ same ("bar code" or barcde or indicia)	USPAT	2002/02/26 11:58
		same (semiconductor or circuit or chip)		
-	85	cover same protect\$ same (semiconductor or circuit or chip)	USPAT	2002/02/26 11:59
		same identif\$		
-	13	cover same protect\$ same (semiconductor or circuit or chip)	USPAT	2002/02/26 12:58
	•	same identif\$ same (transparent or translucent)		
_	1	5970321.pn.	USPAT	2002/02/26 13:00
_	1 1		USPAT	2002/02/26 13:04
-	1	(csp or ("chip scale packag\$")) same (protect\$ or cover)	USPAI	2002/02/20 13.04
	_	same (transparent or clear or translucent)		
-	2	(csp or ("chip scale package")) same (protect\$ or cover)	USPAT	2002/02/26 13:07
		same (transparent or clear or translucent)		
_	2	(csp or ("chip scale")) same (protect\$ or cover) same	USPAT	2002/02/26 13:12
	_	(transparent or clear or translucent)		
_	1	5118369.pn. and code	USPAT	2002/02/26 13:25
	1			
-	31386	"protective layer" or "protective coating" same code same	USPAT	2002/02/26 13:27
		(chip or circuit)		
-	6407	(protect\$ or encapsul\$) same (circuit or chip) same cover	USPAT	2002/02/26 13:27
-	128	(protect\$ adj layer) same indicia	USPAT	2002/02/26 13:34
_	6369	(protect\$ or encapsul\$) same (chip or circuit or	USPAT	2002/02/26 13:47
		semiconductor) and (mold\$ or print\$ or glb) and (transparent_		
	ļ	or translucent)		-
	E-7		HODAT	2002/02/20 42:44
-	57	(protect\$ adj layer) same indicia same (mold\$ or print\$ or	USPAT	2002/02/26 13:41
] ,	glob)	l <u></u>	
-	14935	(protect\$ or encapsul\$) same (chip or circuit or	USPAT	2002/02/26 14:01
		semiconductor) same (mold\$ or print\$ or glob or epoxy same		
		transparent)		
_	2634	(protect\$ or encapsul\$) same (chip or circuit or	USPAT	2002/02/26 13:59
	2007	semiconductor) same identif\$] 55. 7.1	
	40		LICDAT	2002/02/26 42:57
-	13	(protect\$ or encapsul\$) same (chip or circuit or	USPAT	2002/02/26 13:57
		semiconductor) same identif\$ same transparent same cover	<u>.</u>	
-	13	(protect\$ or encapsul\$) same (chip or circuit or	USPAT	2002/02/26 14:00
		semiconductor) same identif\$ same transparent same cover	I	Í

	8	(protect\$ or encapsul\$) same (chip or circuit or	USPAT	2002/02/26 14:11
_	°		USPAI	2002/02/20 14.11
		semiconductor) same (mold\$ or print\$ or glob or epoxy) same transparent same cover same identif\$		
	336		LICDAT	2002/02/26 44:42
-	336	(protect\$ or encapsul\$) same (chip or circuit or	USPAT	2002/02/26 14:13
		semiconductor) same (code or indicia or label) same identif\$		0000/00/00 44 00
-	25	(protect\$ or encapsul\$) same (chip or circuit or	USPAT	2002/02/26 14:32
		semiconductor) same (code or indicia or label) same identif\$		
	1 .	and cover and transparent	l <u></u>	
-	1	5279690.pn. and transparent	USPAT	2002/02/26 14:57
-	1070	mylar same color\$	USPAT	2002/02/26 14:57
-	5	mylar adj color\$	USPAT	2002/02/26 15:09
-	0	5118369.pn. and silicon	USPAT	2002/02/26 15:24
-	50	chip same color same identification	USPAT	2002/02/26 15:44
-	1489	color same identif\$ same (semiconductor or circuit)	USPAT	2002/02/26 15:45
-	24	identif\$ adj3 (semiconductor or circuit) adj3 color	USPAT	2002/02/26 15:49
-	74	identif\$ same semiconductor same color	USPAT	2002/02/26 16:01
-	3514	color adj2 code	USPAT	2002/02/26 16:03
-	824	color adj2 code) same identif\$	USPAT	2002/02/26 16:03
-	67	(color adj2 code) same identif\$ same (circuit or chip or	USPAT	2002/02/26 16:10
		semiconductor)		
-	19	"color coded" adj3 (circuit or semiconductor or chip)	USPAT	2002/02/26 16:11
-	238	((mark\$3 or label\$3 or indicia) adj3 (semiconductor or circuit	USPAT	2002/07/31 10:11
		or integrated or chip)) same cover\$3		
-	15	(mark\$3 or label\$3 or indicia) adj3 (semiconductor or circuit	USPAT	2002/07/31 10:12
		or integrated or chip) adj3 (overlay\$3 or cover\$3)		, i
-	15	((mark\$3 or label\$3 or indicia) adj3 (semiconductor or circuit	USPAT	2002/07/31 10:42
		or integrated or chip)) adj3 cover\$3		
_	0	((mark\$3 or label\$3 or indicia) adj3 (semiconductor or circuit	USPAT	2002/07/31 10:44
		or chip)) same ((transparent or transmissive or translucent or		
		cover\$3) adj3 (irremovable or permanent))		
_	31	((mark\$3 or label\$3 or indicia) adj3 (semiconductor or circuit	USPAT	2002/07/31 11:08
	"	or chip or wafer or component or card or device)) same	001711	2002/07/01 11:00
	:	((transparent or transmissive or translucent) adj3 (overlay\$3		
		or cover\$3))		
_	4	5461545.pn. or 4300184.pn. or 5641997.pn. or 5479049.pn.	USPAT	2002/07/31 11:15
_	2	"encapsulation layer" same CSP	USPAT	2002/07/31 11:15
	68	(coat\$3 or encapsulat\$3) same (layer or film) same (chip or	USPAT	2002/07/31 11:15
•		circuit) same (transparent or translucent or transmissive)	331 \(\)	2002/07/31 11.25
		same (indicia or label or mark\$4)		
	118	(coat\$3 or encapsulat\$3) same (layer or film) same (chip or	USPAT	2002/07/31 11:26
-	110		USPAI	2002/07/51 11.20
		circuit or wafer or semiconductor) same (transparent or		
	100	translucent or transmissive) same (indicia or label or mark\$4)	LICEAT	0000/07/04 44:00
-	108	((coat\$3 or encapsulat\$3 or cover\$3) adj3 (layer or film or	USPAT	2002/07/31 11:29
		material\$3 or coat\$3)) same (chip or circuit or wafer or		
		semiconductor) same (transparent or translucent or		
		transmissive) same (indicia or label or mark\$4)		
-	102	((coat\$3 or encapsulat\$3 or cover\$3) adj3 (layer or film or	USPAT	2002/07/31 14:53
		material\$3 or coat\$3)) same (chip or circuit or wafer or		
		semiconductor) same (transparent or translucent or		
	L	transmissive) same (indicia or label or mark\$3)		